

Docket No.: 288839US0PCT

ATTORNEYS AT LAW

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

RE: Application Serial No.: 10/586,675
Applicants: Ekkehard MUEH, et al.
Filing Date: July 20, 2006
For: SILICON COMPOUNDS FOR PRODUCING SIO₂-CONTAINING
INSULATING LAYERS ON CHIPS
Group Art Unit: 1715
Examiner: MILLER, JR, JOSEPH ALBERT

SIR:

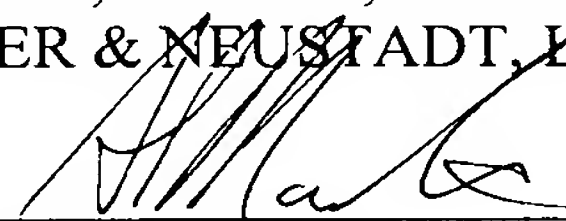
Attached hereto for filing are the following papers:

RESTRICTION RESPONSE

Credit card payment is being made online (if electronically filed), or is attached hereto (if paper filed), in the amount of **\$0.00** to cover any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 C.F.R. 1.136 for any necessary Extension of Time to make the filing of the attached documents timely, please charge or credit the difference to our Deposit Account No. **15-0030**. Further, if these papers are not considered timely filed, then a petition is hereby made under 37 C.F.R. 1.136 for the necessary extension of time.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
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